PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yong Liu	01/25/2008
Hua Yang	01/29/2008
Tiburcio A. Maldo	01/29/2008

RECEIVING PARTY DATA

Name:	Fairchild Semiconductor Corporation
Street Address:	82 Running Hill Road
City:	South Portland
State/Country:	MAINE
Postal Code:	04106

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12025798

CH $40.00 12025798

CORRESPONDENCE DATA

Fax Number: (585)295-8456
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (585) 295-4469
Email: tfitzgerald@hblaw.com
Correspondent Name: Thomas R. FitzGerald, Esq.
Address Line 1: Hiscock & Barclay, LLP
Address Line 2: 2000 HSBC Plaza, 100 Chestnut St.
Address Line 4: Rochester, NEW YORK 14604-2404

ATTORNEY DOCKET NUMBER:	3026303 (69050US.01)
NAME OF SUBMITTER:	Thomas R. FitzGerald

Total Attachments: 4
source=Assignment#page1.tif

source=Assignment#page2.tif
source=Assignment#page3.tif
source=Assignment#page4.tif

FAIRCHILD SEMICONDUCTOR CORPORATION

Assignment

As a below named inventor or joint inventor of an invention or improvement entitled:

FOLDED LEADFRAME MULTIPLE DIE PACKAGE

Attorney Docket No. 3026303 (17732.69050.00)

filed on an even date herewith; and

WHEREAS, FAIRCHILD SEMICONDUCTOR CORPORATION, a Corporation, organized and existing under the laws of the State of Delaware, having its principal office and place of business in the City of South Portland, State of Maine, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer and set over, unto said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, my entire right, title and interest in, to, and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuation applications thereof, and all Letters Patent of the United States of America which may be granted thereof and all reissues and extensions hereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, all rights to register said invention in appropriate registries, and all Letters Patent which may be granted for said invention in any country or countries foreign to the Unites States of America, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

And I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

And I hereby further covenant and agree that I will communicate to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, any fact known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisions, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN TESTIMONY WHEREOF, I authorize and affirm said assignments with the signature(s) set forth below on the indicated date(s).

Inventors:

Yong Liu 01/25/2008

Yong Liu Date

Hua Yang

Tiburcio A. Maldo Date

FAIRCHILD SEMICONDUCTOR CORPORATION

Assignment

As a below named inventor or joint inventor of an invention or improvement entitled:

FOLDED LEADFRAME MULTIPLE DIE PACKAGE

Attorney Docket No. 3026303 (17732.69050.00)

filed on an even date herewith; and

WHEREAS, FAIRCHILD SEMICONDUCTOR CORPORATION, a Corporation, organized and existing under the laws of the State of Delaware, having its principal office and place of business in the City of South Portland, State of Maine, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer and set over, unto said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, my entire right, title and interest in, to, and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuation applications thereof, and all Letters Patent of the United States of America which may be granted thereof and all reissues and extensions hereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, all rights to register said invention in appropriate registries, and all Letters Patent which may be granted for said invention in any country or countries foreign to the Unites States of America, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

And I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

Docket No.:
3026303 (17732.69050.00)

And I hereby further covenant and agree that I will communicate to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, any fact known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisions, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN TESTIMONY WHEREOF, I authorize and affirm said assignments with the signature(s) set forth below on the indicated date(s).

Inventors:

Yong Liu
Date

杨华
Jan. 29. 2008
Hua Yang

Jan-29-2008
Tiburcio A. Maldo
Date